

SYSTEM AND METHOD FOR CONTROLLING TEMPERATURE DURING BURN-IN

ABSTRACT

5 Systems and methods for reducing temperature dissipation during burn-in testing are described. Devices under test are each subject to a body bias voltage. The body bias voltage can be used to control junction temperature (e.g., temperature measured at the device under test). The body bias voltage applied to each device under test can be adjusted device-by-device to achieve essentially the
10 same junction temperature at each device.